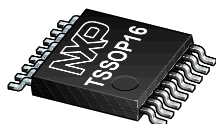

SOT403-1

plastic, thin shrink small outline package; 16 leads; 0.65 mm pitch; 5 mm x 4.4 mm x 1.1 mm body

9 January 2017 Package information

1. Package summary

Dimensions (mm)	5 x 4.4 x 1.1
Terminal position code	D (double)
Package type descriptive code	TSSOP16
Package outline version code	SOT403-1
Manufacturer package code	SOT403
Package type industry code	TSSOP16
Package outline version description	plastic, thin shrink small outline package; 16 leads; 0.65 mm pitch; 5 mm x 4.4 mm x 1.1 mm body
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P
JEDEC package outline code	MO-153
Handling precautions	IC26_CHAPTER_3_2000
Thermal design considerations	IC26_CHAPTER_6_2000
Mounting method type	S (surface mount)
Generic mounting and soldering information	AN10365_3
Reflow soldering footprint	SOT403-1_fp_reflow
Wave soldering footprint	SSOP-TSSOP-VSO-WAVE
Package life cycle status	REL
Major version date	9-10-2008
Minor version date	9-7-2012
Security status	COMPANY PUBLIC
Modified date	15-11-2012
Issue date	18-2-2003
Web publication date	28-11-2012
Initial web publication date	18-1-2011
Customer specific indicator	N
Maturity	Product
Package author	Nair Deepa
Package approver	Nair Deepa

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
A_2	package height		0.8	-	0.9	0.95	mm

Symbol	Parameter		Min	Typ	Nom	Max	Unit
A	seated height		-	-	1.1	1.1	mm
D	package length		4.9	-	5	5.1	mm
E	package width		4.3	-	4.4	4.5	mm
e	nominal pitch		-	-	0.65	-	mm
n_2	actual quantity of termination		-	-	16	-	

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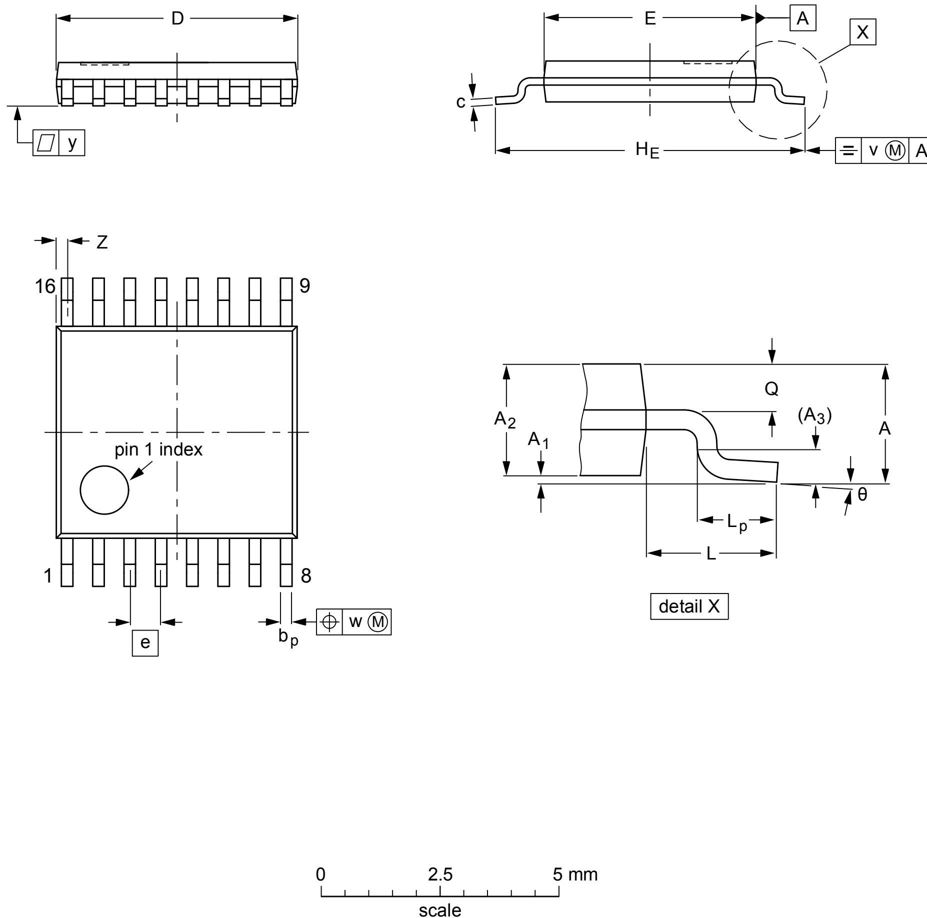
2. Package outline

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm **SOT403-1**



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				~~99-12-27~~ 03-02-18

Fig. 1. Package outline TSSOP16 (SOT403-1)

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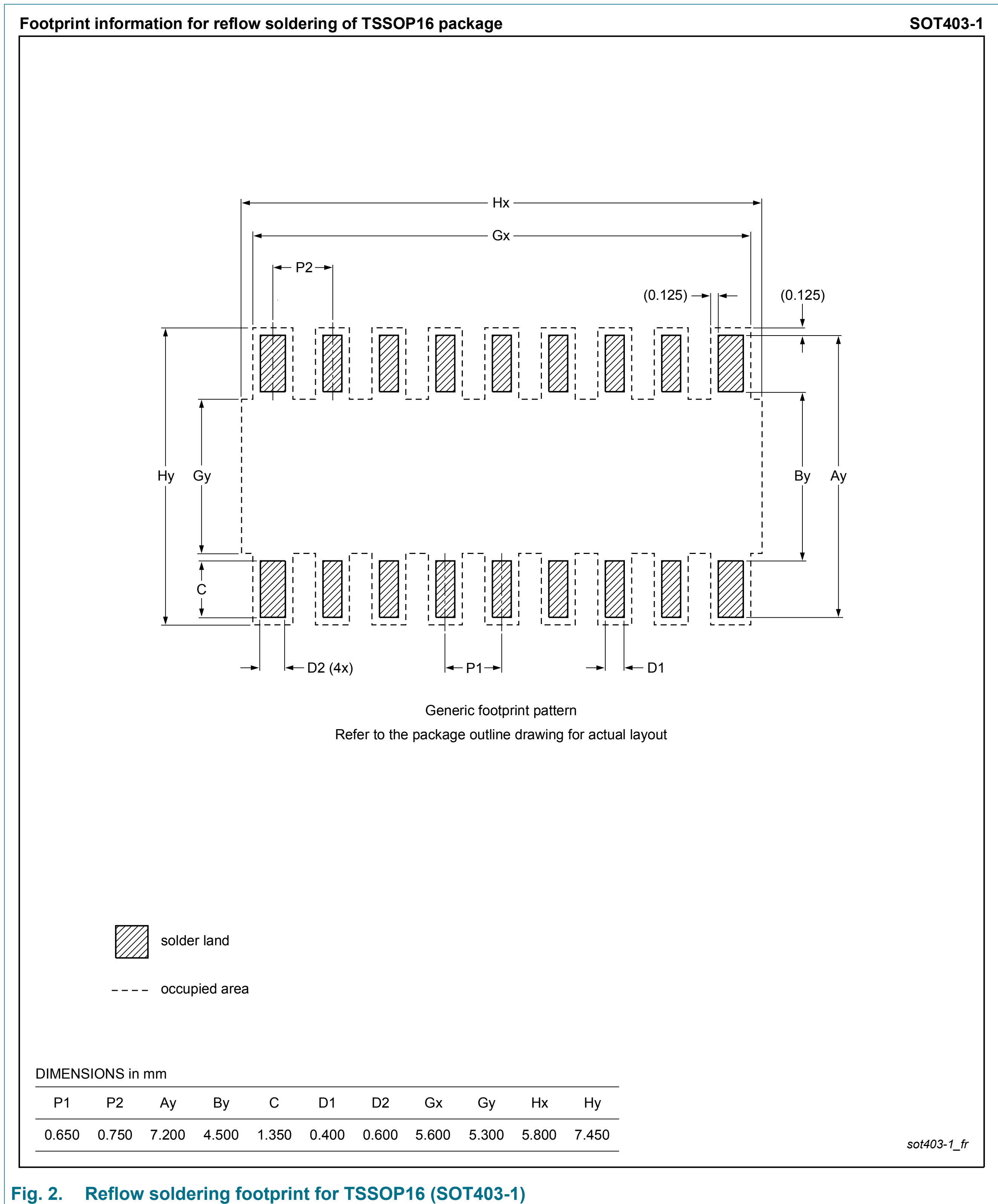
3. Soldering



P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.650	0.750	7.200	4.500	1.350	0.400	0.600	5.600	5.300	5.800	7.450

Fig. 2. Reflow soldering footprint for TSSOP16 (SOT403-1)

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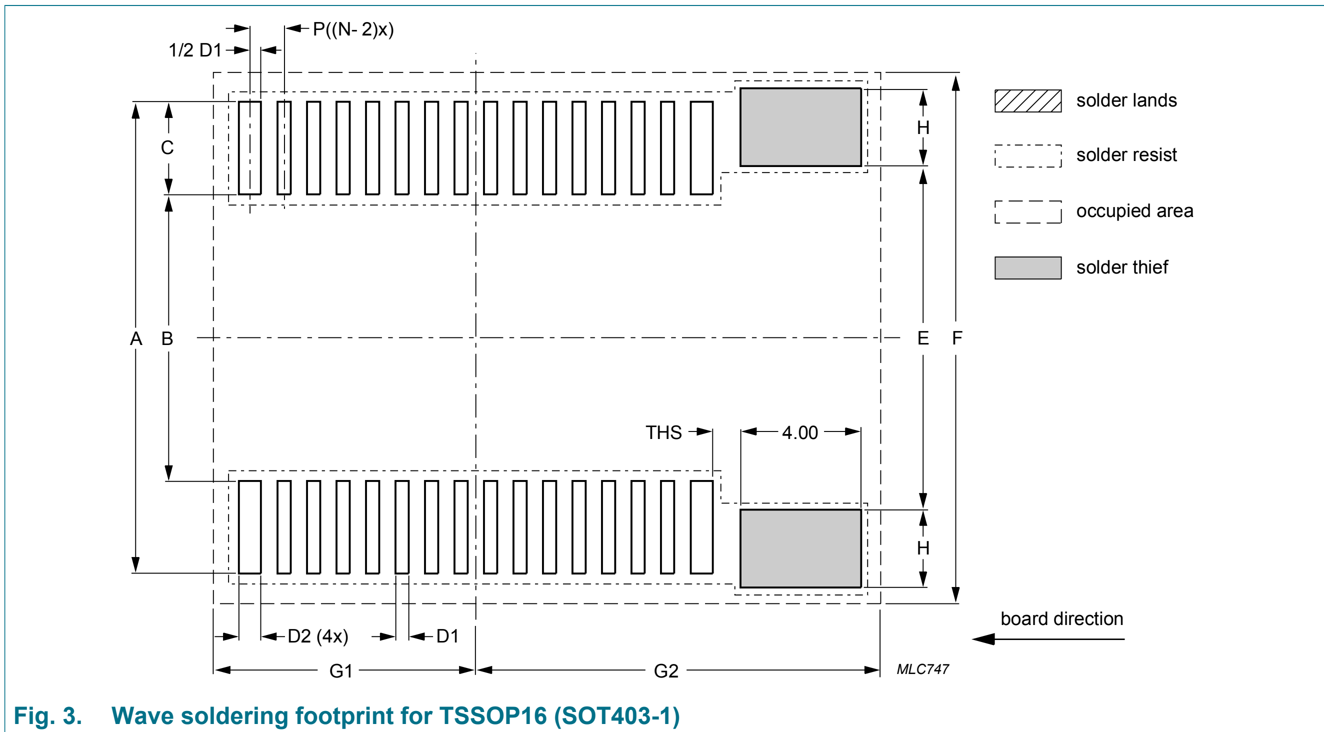

Fig. 3. Wave soldering footprint for TSSOP16 (SOT403-1)

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